

**REMARKS**

In the above-identified Office Action, claims 9-11 have been rejected under 35 U.S.C. §112. The Examiner has stated that there is no support in the originally filed application for defects to be uniformly distributed in a region consisting essentially of a central region. In response, Applicants have amended the application to specifically define the fact that the wafer has a surface region and a bulk region, and that oxide precipitates are uniformly distributed in the bulk region. Applicants have maintained this phrase noting that support for this phrase may be found in the specification on pages 16, 17 and 23.

Claims 9-11 have been rejected as failing to comply with a written description requirement. The Examiner has stated that the phrase "said first step being performed first after a wafer slicing process", is not found in the specification. Applicants note that the example on page 33 of the specification shows just this sequence.

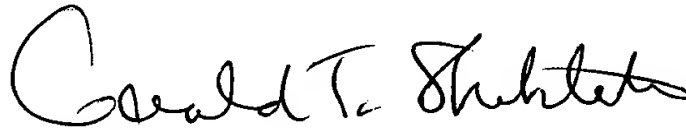
In addition, claims 9-11 have been rejected under 35 U.S.C. §112 as indefinite or use of the term "defects". Applicants have replaced the term "defects" with "oxide precipitates" and as such believes the amended phrase to be acceptable.

In addition to the above, claims 9-13 have been rejected as unpatentable over the Japanese reference Furuya and the English abstract and the computed translation. Applicants have amended the claims so that heat treating method consists entirely of a first step and a second step. Neither of the methods of Furuya and Bischoff utilized the exact heat treatment procedure as set forth in more detail in previous amendments herein and accordingly, the amended claims should be patentable thereover.

Applicants hereby request reconsideration and reexamination thereof.

With the above amendments and remarks, this application is considered ready for allowance and Applicants earnestly solicit an early notice of same. Should the Examiner be of the opinion that a telephone conference would expedite prosecution of the subject application, he is respectfully requested to call the undersigned at the below-listed number.

Respectfully submitted,  
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